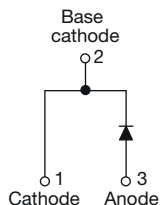


# Hyperfast Rectifier, 15 A FRED Pt®



TO-220AC 2L



## FEATURES

- Hyperfast recovery time, extremely low  $Q_{rr}$
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	15 A
$V_R$	600 V
$V_F$ at $I_F$	1.55 V
$t_{rr}$ (typ.)	18 ns
$T_J$ max.	175 °C
Package	TO-220AC 2L
Circuit configuration	Single

## DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		600	V
Average rectified forward current in DC	$I_{F(AV)}$	$T_C = 141\text{ °C}$	15	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$	120	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

## ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	$V_F$	$I_F = 15\text{ A}$	-	2.5	3.4	
		$I_F = 15\text{ A}, T_J = 150\text{ °C}$	-	1.55	2	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	0.02	36	$\mu\text{A}$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	40	250	
Junction capacitance	$C_T$	$V_R = 600\text{ V}$	-	12	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	17	23	ns
		$I_F = 15\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	18	30	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	20	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	45	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	2.7	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	5.5	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	26	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	130	-	
Reverse recovery time	$t_{rr}$	$I_F = 15\text{ A}$ , $di_F/dt = 800\text{ A}/\mu\text{s}$ , $V_R = 390\text{ V}$	-	32	-	ns
Peak recovery current	$I_{RRM}$		-	17	-	A
Reverse recovery charge	$Q_{rr}$		-	290	-	nC

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction-to-case	$R_{thJC}$		-	1.2	1.4	$^{\circ}\text{C}/\text{W}$
			-	3.7	4.3	
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount	-	-	70	
Typical thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2	-	g
			-	0.07	-	oz.
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC 2L	ETX1506			

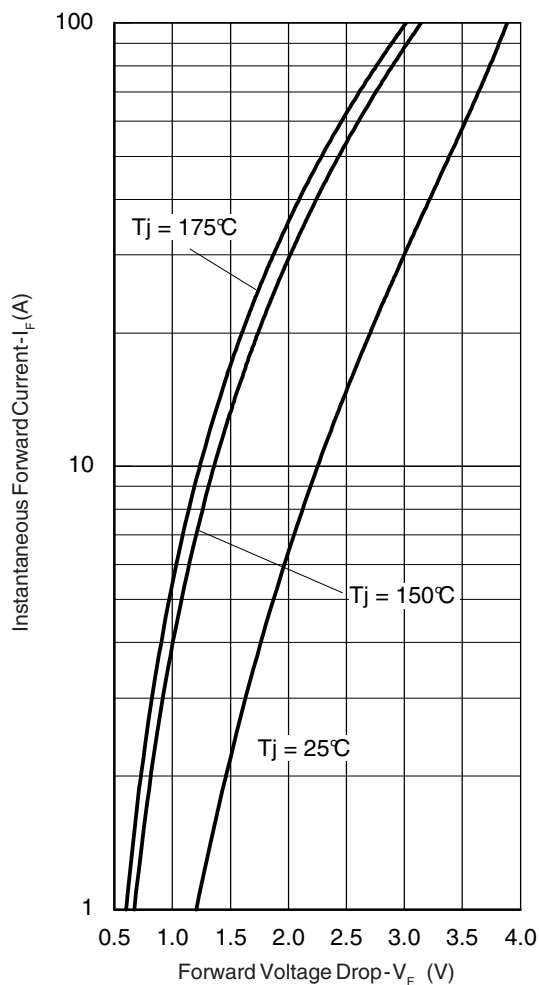


Fig. 1 - Typical Forward Voltage Drop Characteristics

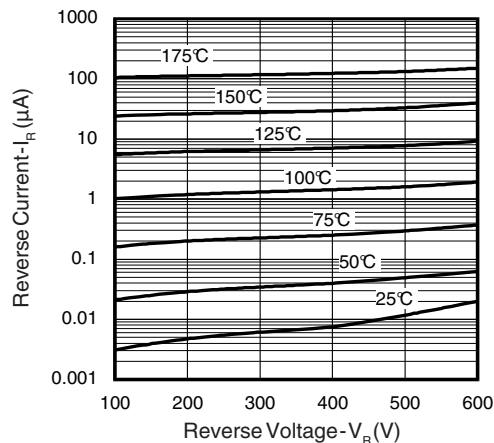


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

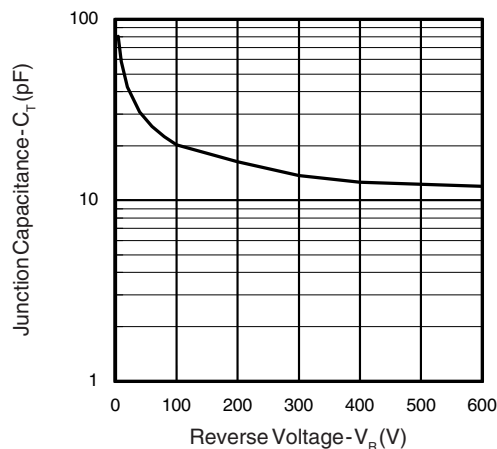
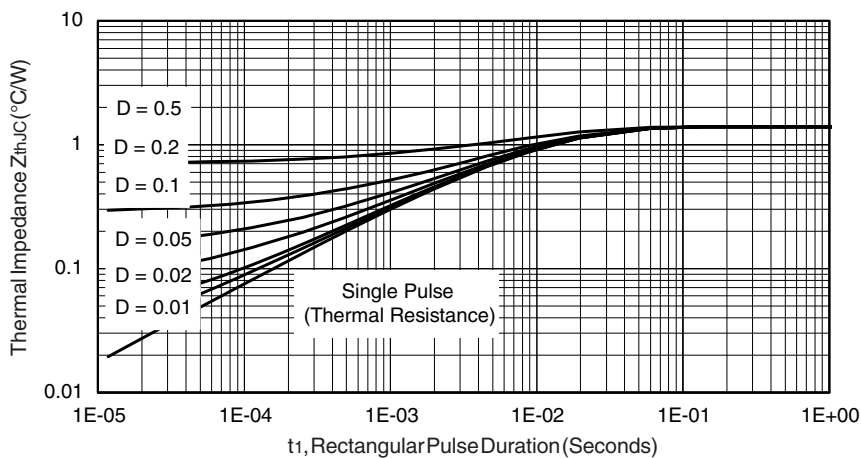


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

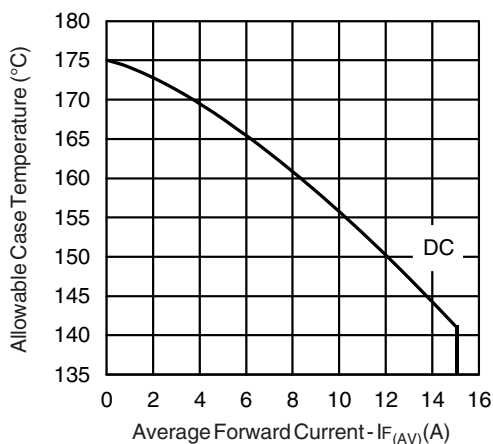


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

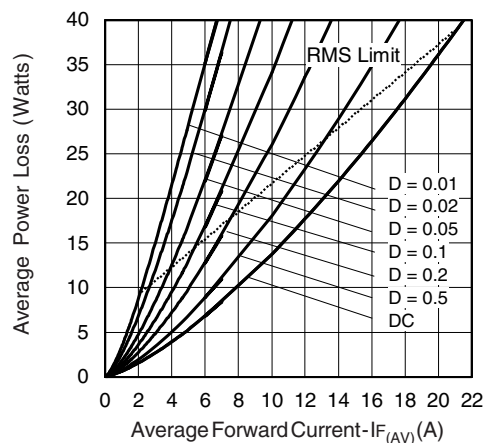


Fig. 6 - Forward Power Loss Characteristics

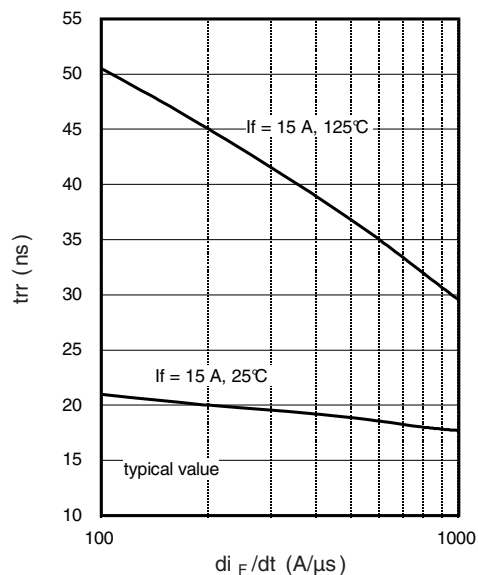


Fig. 7 - Typical Reverse Recovery vs.  $di_F/dt$

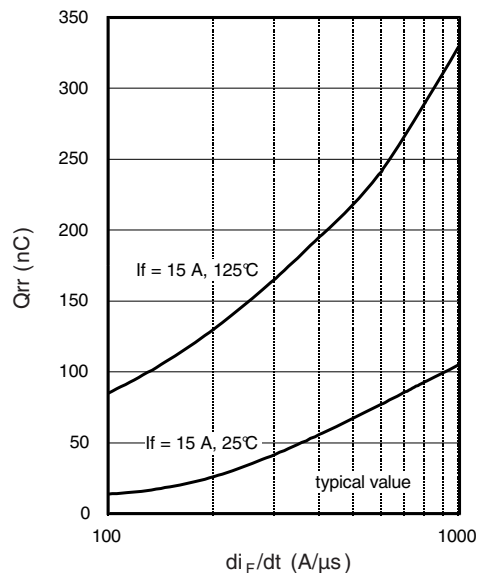


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$

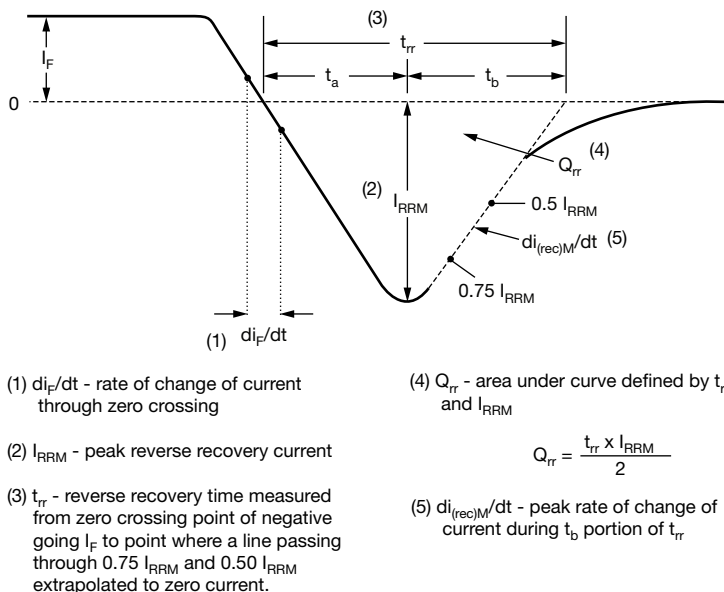


Fig. 9 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

Device code	VS-	E	T	X	15	06	-M3
	1	2	3	4	5	6	7

- 1** - Vishay Semiconductors product
- 2** - Circuit configuration:  
E = single
- 3** - T = 2L TO-220AC
- 4** - X = hyperfast recovery time
- 5** - Current code: 15 = 15 A
- 6** - Voltage code: 06 = 600 V
- 7** - Environmental digit:  
-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-ETX1506-M3	50	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?96156">www.vishay.com/doc?96156</a>
Part marking information	<a href="http://www.vishay.com/doc?95391">www.vishay.com/doc?95391</a>



### TO-220AC 2L

**DIMENSIONS** in millimeters and inches



Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.50	2.92	0.098	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.35	0.585	0.604	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	13.30	0.460	0.524	6, 7
E	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
e	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
Ø P	3.54	3.91	0.139	0.154	
Q	2.60	3.00	0.102	0.118	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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